5 V ECL Quint 2-Input AND/NAND Gate

MC100E104

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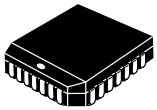


PLCC−28
FN SUFFIX
CASE 776−02

Description

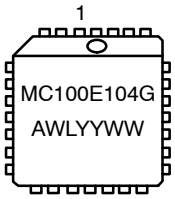
The MC100E104 is a quint 2-input AND/NAND gate. The function output F is the OR of all five AND gate outputs, while $\overline{F}$ is the NOR. The Q outputs need not be terminated if only the F outputs are to be used.

The 100 Series contains temperature compensation.

Features

- 600 ps Max. Propagation Delay
- OR/NOR Function Outputs
- PECL Mode Operating Range: V_{CC} = 4.2 V to 5.7 V with V_{EE} = 0 V
- NECL Mode Operating Range: V_{CC} = 0 V with V_{EE} = −4.2 V to −5.7 V
- Internal Input 50 kΩ Pulldown Resistors
- ESD Protection:
  - > 2 kV Human Body Model
  - > 200 V Machine Model
- Meets or Exceeds JEDEC Spec EIA/JESD78 IC Latchup Test
- Moisture Sensitivity: Level 3 (Pb-Free) (For Additional Information, see Application Note AND8003/D)
- Flammability Rating: UL 94 V−0 @ 0.125 in, Oxygen Index: 28 to 34
- Transistor Count = 134 Devices
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant

MARKING DIAGRAM*



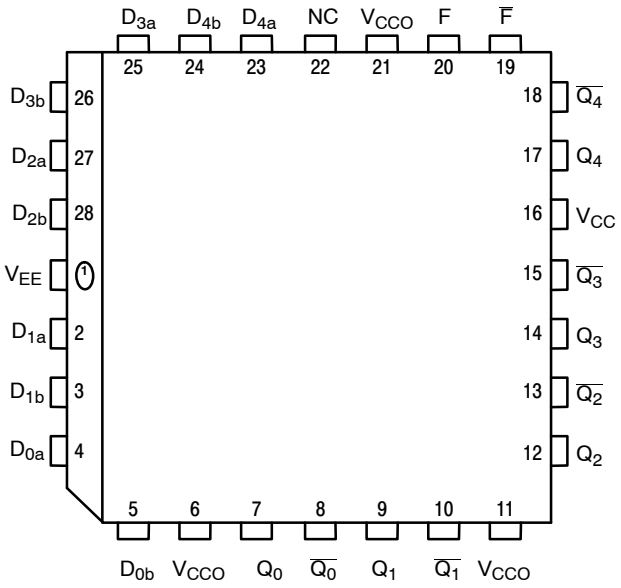
A	= Assembly Location
WL	= Wafer Lot
YY	= Year
WW	= Work Week
G	= Pb-Free Package

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

Device	Package	Shipping†
MC100E104FNR2G	PLCC−28 (Pb-Free)	500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



All V_{CC} and V_{CCO} pins are tied together on the die.

Warning: All V_{CC}, V_{CCO}, and V_{EE} pins must be externally connected to Power Supply to guarantee proper operation.

Figure 1. 28-Lead Pinout (Top View)

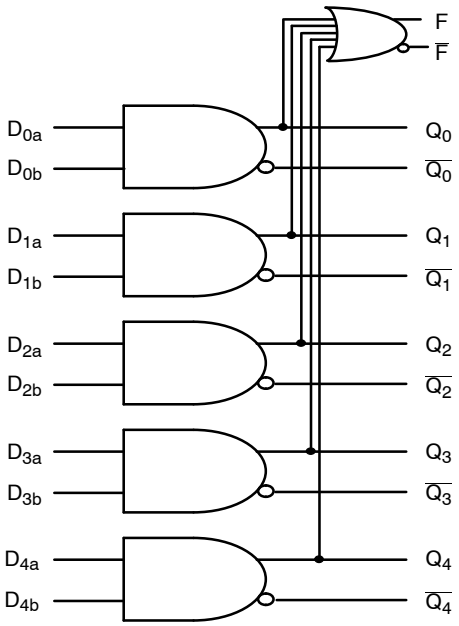


Figure 2. Logic Diagram

Table 1. PIN DESCRIPTION

PIN	FUNCTION
D_{0a} – D_{4b}	ECL Data Inputs
Q_0 – Q_4	ECL AND Outputs
$\overline{Q_0}$ – $\overline{Q_4}$	ECL NAND Outputs
F	ECL OR Output
$\overline{F}$	ECL NOR Output
V_{CC}, V_{CCO}	Positive Supply
V_{EE}	Negative Supply
NC	No Connect

Table 2. FUNCTION OUTPUTS

F =	$(D_{0a} \bullet D_{0b}) + (D_{1a} \bullet D_{1b}) + (D_{2a} \bullet D_{2b}) + (D_{3a} \bullet D_{3b}) + (D_{4a} \bullet D_{4b})$

Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V_{CC}	PECL Mode Power Supply	V_{EE} = 0 V		8	V
V_{EE}	NECL Mode Power Supply	V_{CC} = 0 V		−6	V
V_I	PECL Mode Input Voltage NECL Mode Input Voltage	V_{EE} = 0 V V_{CC} = 0 V	$V_I \le V_{CC}$ $V_I \ge V_{EE}$	6 −6	V
I_{out}	Output Current	Continuous Surge		50 100	mA
T_A	Operating Temperature Range			0 to +85	°C
T_{stg}	Storage Temperature Range			−65 to +150	°C
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	PLCC−28 PLCC−28	63.5 43.5	°C/W
θ_{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	PLCC−28	22 to 26	°C/W
T_{sol}	Wave Solder (Pb-Free)			265	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 4. 100E SERIES PECL DC CHARACTERISTICS (V_{CCx} = 5.0 V; V_{EE} = 0.0 V (Note 1))

Symbol	Characteristic	−40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current		38	46		38	46		44	53	mA
V_{OH}	Output HIGH Voltage (Note 2)	3975	4050	4120	3975	4050	4120	3975	4050	4120	mV
V_{OL}	Output LOW Voltage (Note 2)	3190	3295	3380	3190	3255	3380	3190	3260	3380	mV
V_{IH}	Input HIGH Voltage	3835	3975	4120	3835	3975	4120	3835	3975	4120	mV
V_{IL}	Input LOW Voltage	3190	3355	3525	3190	3525	3355	3190	3355	3525	mV
I_{IH}	Input HIGH Current			200			200			200	μA
I_{IL}	Input LOW Current	0.5	0.3		0.5	0.25		0.5	0.2		μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

1. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary −0.46 V / +0.8 V.
2. Outputs are terminated through a 50 Ω resistor to V_{CC} − 2.0 V.

Table 5. 100E SERIES NECL DC CHARACTERISTICS (V_{CCx} = 0 V; V_{EE} = −5.0 V (Note 1))

Symbol	Characteristic	−40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current		38	46		38	46		44	53	mA
V_{OH}	Output HIGH Voltage (Note 2)	−1025	−950	−880	−1025	−950	−880	−1025	−950	−880	mV
V_{OL}	Output LOW Voltage (Note 2)	−1810	−1705	−1620	−1810	−1745	−1620	−1810	−1740	−1620	mV
V_{IH}	Input HIGH Voltage	−1165	−1025	−880	−1165	−1025	−880	−1165	−1025	−880	mV
V_{IL}	Input LOW Voltage	−1810	−1645	−1475	−1810	−1645	−1475	−1810	−1645	−1475	mV
I_{IH}	Input HIGH Current			200			200			200	μA
I_{IL}	Input LOW Current	0.5	0.3		0.5	0.25		0.5	0.2		μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

1. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary −0.46 V / +0.8 V.
2. Outputs are terminated through a 50 Ω resistor to V_{CC} − 2.0 V.

Table 6. AC CHARACTERISTICS (V_{CCx}= 5.0 V; V_{EE} = 0.0 V or V_{CCx} = 0.0 V; V_{EE} = −5.0 V (Note 1))

		−40°C			25°C			85°C			
Symbol	**Characteristic**	**Min**	**Typ**	**Max**	**Min**	**Typ**	**Max**	**Min**	**Typ**	**Max**	**Unit**
f_{MAX}	Maximum Toggle Frequency		700			700			700		MHz
t_{PLH} t_{PHL}	Propagation Delay to Output D to Q D to F	 225 500	 385 725	 600 1000	 225 500	 385 725	 600 1000	 225 500	 385 725	 600 1000	ps
t_{SKEW}	Within-Device Skew (Note 2) D to Q		 75			 75			 75		ps
t_{JITTER}	Random Clock Jitter (RMS)		< 1			< 1			< 1		ps
t_r t_f	Rise/Fall Time (20−80%) Q F	 100 300	 425 475	 700 700	 100 300	 425 475	 700 700	 100 300	 425 475	 700 700	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

1. V_{EE} can vary −0.46 V / +0.8 V.
2. Within-device skew is defined as identical transitions on similar paths through a device.

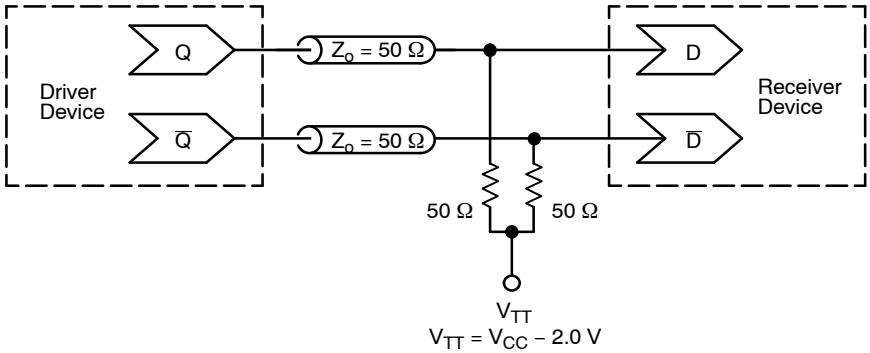


Figure 3. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D – Termination of ECL Logic Devices)

Resource Reference of Application Notes

AN1405/D – ECL Clock Distribution Techniques

AN1406/D – Designing with PECL (ECL at +5.0 V)

AN1503/D – ECLinPS™ I/O SPiCE Modeling Kit

AN1504/D – Metastability and the ECLinPS Family

AN1568/D – Interfacing Between LVDS and ECL

AN1642/D – The ECL Translator Guide

AND8001/D – Odd Number Counters Design

AND8002/D – Marking and Date Codes

AND8020/D – Termination of ECL Logic Devices

AND8066/D – Interfacing with ECLinPS

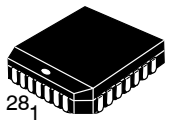
AND8090/D – AC Characteristics of ECL Devices

MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

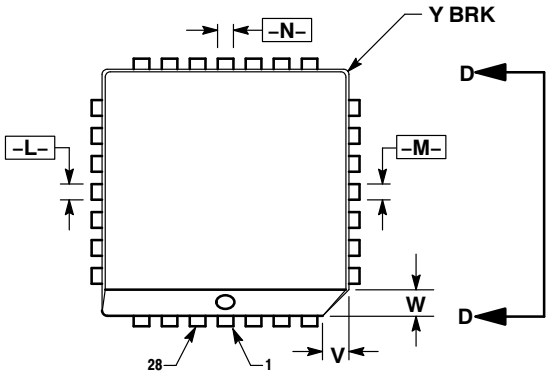
ON Semiconductor®

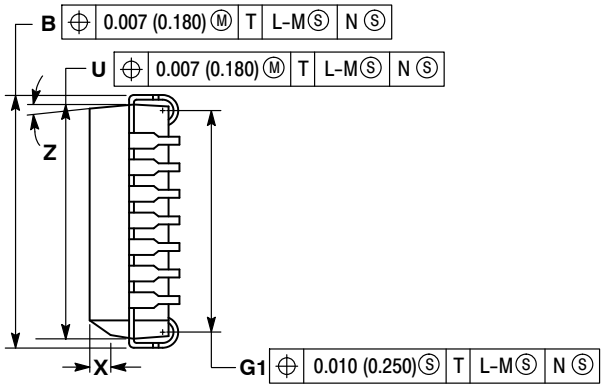
28 LEAD PLCC
CASE 776−02
ISSUE G

DATE 06 APR 2021

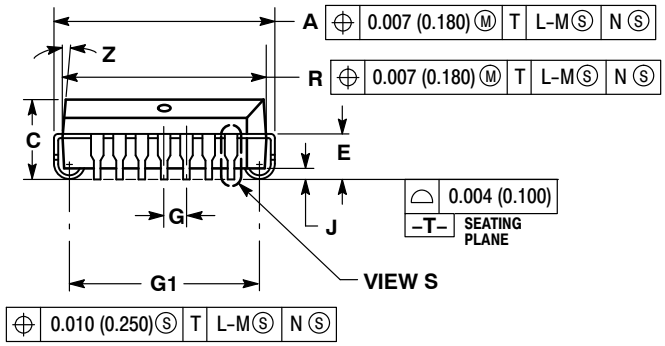


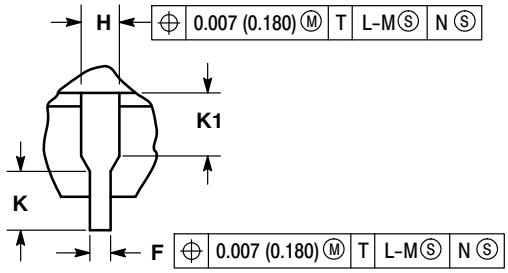
SCALE 1:1





VIEW D–D



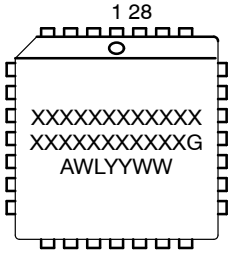


VIEW S

NOTES:
1. DATUMS –L–, –M–, AND –N– DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM –T–, SEATING PLANE.
3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
4. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
5. CONTROLLING DIMENSION: INCH.
6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.485	0.495	12.32	12.57
B	0.485	0.495	12.32	12.57
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.021	0.33	0.53
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	---	0.51	---
K	0.025	---	0.64	---
R	0.450	0.456	11.43	11.58
U	0.450	0.456	11.43	11.58
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	---	0.020	---	0.50
Z	2°	10°	2°	10°
G1	0.410	0.430	10.42	10.92
K1	0.040	---	1.02	---

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

DOCUMENT NUMBER:	**98ASB42596B**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped “CONTROLLED COPY” in red.
DESCRIPTION:	**28 LEAD PLCC**	**PAGE 1 OF 1**

PUBLICATION ORDERING INFORMATION

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